ADVANCED MEMORY SYSTEMS

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Announcement

Homework 5 will be released tonight (the last one ③)

This lecture

- Memory addressing/scheduling
- DRAM refresh
- Emerging technologies

Recall: DRAM Control Tasks

Refresh management

Periodically replenish the DRAM cells (burst vs. distributed)

Address mapping

Distribute the requests to destination banks (load balancing)

Request scheduling

Generate a sequence of commands for memory requests

Reduce overheads by eliminating unnecessary commands

Power management

Keep the power consumption under a cap

Error detection/correction

Detect and recover corrupted data

Address Mapping

□ A memory request

Type Address Data

Address is used to find the location in memory

Channel, rank, bank, row, and column IDs

Example physical address format

Row ID	Channel ID	Rank ID	Bank ID	Column ID
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A 4GB channel, 2 ranks, 4 banks/rank, 8KB page

Address Mapping

A memory request

Type Address Data

Address is used to find the location in memory

Channel, rank, bank, row, and column IDs

Example physical address format

Row ID	Channel ID	Rank ID	Bank ID	Column ID
16	0	1	2	13

A 4GB channel, 2 ranks, 4 banks/rank, 8KB page











Find the total number of commands using the following address mapping scheme



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Command Scheduling

Write buffering

Writes can wait until reads are done

- Controller queues DRAM commands
 - Usually into per-bank queues
 - Allows easily reordering ops. meant for same bank
- Common policies
 - First-Come-First-Served (FCFS)
 - First-Ready First-Come-First-Served (FR-FCFS)

Command Scheduling

- First-Come-First-Served
 - Oldest request first
- First-Ready First-Come-First-Served
 - Prioritize column changes over row changes
 - Skip over older conflicting requests
 - Find row hits (on queued requests)
 - Find oldest
 - If no conflicts with in-progress request \rightarrow good
 - Otherwise (if conflicts), try next oldest

READ(B0,R0,C0) READ(B0,R1,C0) READ(B0,R0,C1) FCFS

READ(B0,R0,C0) READ(B0,R1,C0) READ(B0,R0,C1) FCFS



READ(B0,R0,C0) READ(B0,R1,C0) READ(B0,R0,C1) FCFS



■ FR-FCFS

READ(B0,R0,C0) READ(B0,R1,C0) READ(B0,R0,C1) FCFS





Row Buffer Management Policies

Open-page policy

- After access, keep page in DRAM row buffer
- If access to different page, must close old one first
 - Good if lots of locality
- Close-page policy
 - After access, immediately close page in DRAM row buffer
 - If access to different page, old one already closed
 - Good if no locality (random access)

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- DRAM requires the cells' contents to be read and written periodically
 - Burst refresh: refresh all of the cells each time
 - Simple control mechanism
 - Distributed refresh: a group of cells are refreshed
 - Avoid blocking memory for a long time
- Recently accessed rows need not to be refreshed
 - Smart refresh





Error Detection/Correction

- Data in memory may be corrupted
 - Many reasons: leakage, alpha particles, hard errors
- Can errors be detected?
 - Error detection codes: additional parity bits
- Can errors be corrected?
 - Error correction codes: ECC bits are added to data
- Single-Error Correction, Double-Error Detection
 - Commonly used in memory systems

ECC DIMM

An additional DRAM chip is used for storing SECDED ECC bits for error correction



Emerging Technologies

DRAM Cell Structure

One-transistor, one-capacitor

Realizing the capacitor is challenging



- 1T-1C DRAM
- Charge based sensing
- Volatile

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Memory Scaling in Jeopardy

Scaling of semiconductor memories greatly challenged beyond 20nm

Example: DRAM



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Example: DRAM



Why DRAM Slow?

Logic VLSI Process: optimized for better transistor performance

DRAM VLSI Process: optimized for low cost and low leakage



How to reduce distance?

3D Die-Stacking

Different devices are stacked on top of each other
Layers are connected by through-silicon vias (TSVs)





- □ Why?
 - Communication between devices bottlenecked by limited I/O pins
 - Integrating heterogeneous elements on a single wafer is expensive and suboptimal

3D Stacked Memory

- Hybrid Memory Cube (HMC)
 - A logic layer at the bottom



High Bandwidth Memory (HBM)
Silicon interposer at the bottom





Emerging Non Volatile Memory

Resistive Memory Technologies

Key concept: replace DRAM cell capacitor with a programmable resistor





- 1T-1C DRAM
- Charge based sensing
- Volatile

- 1T-1R STT-MRAM, PCM, RRAM
- Resistance based sensing
- Non-volatile

Leading Contenders

STT-MRAM



[Halupka, et al. ISSCC'10]

- Limited to single-level cell
- 3D un-stackable
- + High endurance ($\sim 10^{15}$)
- $+ \sim 4$ ns switching time
- $+ \sim 50 \text{uW}$ switching

power

PCM-RAM



[Pronin. EETime'13]

- + Multi-level cell capable
- + 4F² 3D-stackable cell
- Endurance: $\sim 10^9$ writes
- ~ 100 ns switching time
- ~300uW switching power

R-RAM



[Henderson. InfoTracks'11]

- + Multi-level cell capable
- + 4F² 3D-stackable cell
- Endurance: 10⁶~10¹² writes
- $+ \sim 5$ ns switching time
- $+ \sim 50 uW$ switching power



Positioning of Resistive Memories

